TO-251



SiHU6N80E-VB Datasheet

N-Channel 800V (D-S) Super Junction Power MOSFET

| PRODUCT SUMMARY | | | | | |
|---------------------------------------|-----------------|-------|--|--|--|
| V_{DS} (V) at T_J max. | 800 | | | | |
| R _{DS(on)} typ. (Ω) at 25 °C | $V_{GS} = 10 V$ | 0.850 | | | |

FEATURES

- Low figure-of-merit (FOM) Ron x Qg
- Low input capacitance (Ciss)
- Reduced switching and conduction losses
- Ultra low gate charge (Q_g)
- Avalanche energy rated (UIS)



S N-Channel MOSFET

- APPLICATIONS
- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
 - High-intensity discharge (HID)
 - Fluorescent ballast lighting
- Industrial
 - Welding
 - Induction heating
 - Motor drives
 - Battery chargers
 - Renewable energy
 - Solar (PV inverters)

| ABSOLUTE MAXIMUM RATINGS (T _C | = 25 °C, unl | ess otherwis | se noted) | | | |
|---|-------------------------|---|-----------------------------------|-------------|-------|--|
| PARAMETER | | | SYMBOL | LIMIT | UNIT | |
| Drain-source voltage | | | V _{DS} | 800 | V | |
| Gate-source voltage | | | V _{GS} | ± 30 | V | |
| Continuous drain current (T _{.1} = 150 °C) | V _{GS} at 10 V | T _C = 25 °C T _C = 100 °C | - I _D | 6 | | |
| Continuous drain current $(1) = 150^{\circ}$ C) | V _{GS} at 10 V | T _C = 100 °C | | 4 | А | |
| Pulsed drain current ^a | | | I _{DM} | 18 | | |
| Linear derating factor | | | | 1.7 | W/°C | |
| Single pulse avalanche energy ^b | | | E _{AS} | 580 | mJ | |
| Maximum power dissipation | | | PD | 210 | W | |
| Operating junction and storage temperature range | | | T _J , T _{stg} | -55 to +150 | °C | |
| Drain-source voltage slope | T _J = 125 °C | | -10.77-11 | 50 | 1//22 | |
| Reverse diode dV/dt ^d | | | dV/dt | 5.1 | V/ns | |
| Soldering recommendations (peak temperature) ^c | For 10 s | | | 260 | °C | |

Notes

a. Repetitive rating; pulse width limited by maximum junction temperature

b. V_{DD} = 100 V, starting T_J = 25 °C, L = 30 mH, R_g = 25 $\Omega,\,I_{AS}$ = 8.0 A

c. 1.6 mm from case

d. $I_{SD} \leq I_D$, dl/dt = 100 A/µs, starting T_J = 25 °C

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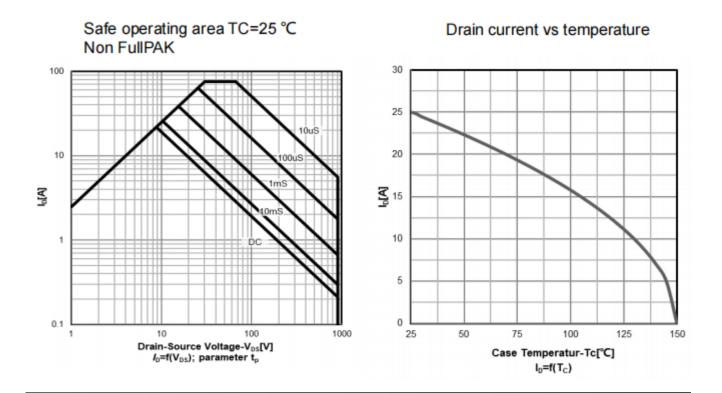
| THERMAL RESISTANCE RAT | NGS | | | | | | | |
|---|---------------------|--|--------------------------------------|----------------------------|------|--------|------|-----|
| PARAMETER | SYMBOL | TYP. | | MAX. | | UNIT | | |
| Maximum junction-to-ambient | R _{thJA} | - | | 62 | | 00.004 | | |
| Maximum junction-to-case (drain) | R _{thJC} | - | - 0.65 | | | °C/W | | |
| | | | | | | | | |
| SPECIFICATIONS (T _J = 25 $^{\circ}$ C, u | unless otherwi | se noted) | | | | | | |
| PARAMETER | SYMBOL | TES | T CONDIT | IONS | MIN. | TYP. | MAX. | UNI |
| Static | | | | | | | | |
| Drain-source breakdown voltage | V _{DS} | V _{GS} = | = 0 V, I _D = 2 | 250 µA | 800 | - | - | V |
| V _{DS} temperature coefficient | $\Delta V_{DS}/T_J$ | Reference | e to 25 °C, | $I_D = 1 \text{ mA}$ | - | 1.08 | - | V/° |
| Gate-source threshold Voltage (N) | V _{GS(th)} | V _{DS} = | = V _{GS} , I _D = | 250 µA | 2.0 | - | 4.0 | V |
| Gate-source leakage | | $V_{GS} = \pm 20 \text{ V}$ | | - | - | ± 100 | nA | |
| | I _{GSS} | | $V_{GS} = \pm 30$ | V | - | - | ± 1 | μA |
| Zero gate voltage drain current | | V _{DS} = | = 800 V, V _C | _{as} = 0 V | - | - | 1 | |
| | IDSS | V _{DS} = 640 V, V _{GS} = 0 V, T _J = 125 °C | | - | - | 10 | μA | |
| Drain-source on-state resistance | R _{DS(on)} | $V_{GS} = 10 V$ | I | _D =2 A | - | 0.850 | - | Ω |
| Forward transconductance | 9 _{fs} | $V_{DS} = 30 \text{ V}, \text{ I}_{D} = 2 \text{ A}$ | | - | 8.7 | - | S | |
| Dynamic | • | | | | • | | • | |
| Input capacitance | C _{iss} | $V_{GS} = 0 V,$ $V_{DS} = 100 V,$ f = 1 MHz | | - | 2600 | - | pF | |
| Output capacitance | C _{oss} | | | - | 81 | - | | |
| Reverse transfer capacitance | C _{rss} | | | - | 9 | - | | |
| Effective output capacitance, energy related ^a | C _{o(er)} | $V_{DS} = 0 V$ to 480 V, $V_{GS} = 0 V$ | | - | 58 | - | | |
| Effective output capacitance, time related ^b | C _{o(tr)} | | | - | 296 | - | | |
| Total gate charge | Qg | | | | - | 61 | 122 | 1 |
| Gate-source charge | Q _{gs} | $V_{GS} = 10 \text{ V}$ $I_D = 6 \text{ A}, V_{DS} = 480 \text{ V}$ | | - | 16 | - | nC | |
| Gate-drain charge | Q _{gd} | | | - | 20 | - | | |
| Turn-on delay time | t _{d(on)} | | | | - | 22 | 44 | |
| Rise time | t _r | V_{DD} = 480 V, I _D = 6 A, V _{GS} = 10 V, R _g = 9.1 Ω f = 1 MHz, open drain | | -64 | - | 24 | 48 | 1 |
| Turn-off delay time | t _{d(off)} | | | - | 71 | 142 | ns | |
| Fall time | t _f | | | - | 26 | 52 | | |
| Gate input resistance | R _g | | | 0.3 | 0.7 | 1.4 | Ω | |
| Drain-Source Body Diode Characteristi | | | | | • | · | | |
| Continuous source-drain diode current | ١ _S | MOSFET symbol showing the integral reverse p - n junction diode | | - | - | 6 | - | |
| Pulsed diode forward current | I _{SM} | | | - | - | 12 | A | |
| Diode forward voltage | V _{SD} | $T_J = 25 \ ^{\circ}C, \ I_S = 6 \ A, \ V_{GS} = 0 \ V$ | | - | - | 1.2 | V | |
| Reverse recovery time | t _{rr} | | | | - | 416 | 832 | ns |
| Reverse recovery charge | Q _{rr} | $T_J = 2$ | 5 °C, $I_F = I_2$ | S = 6 A, | - | 6.4 | 12.8 | μΟ |
| Reverse recovery current | I _{RRM} | ai/at = | 100 A/µs, \ | $v_{\rm R} = 25 \text{ V}$ | - | 27 | - | A |

Notes

a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS}

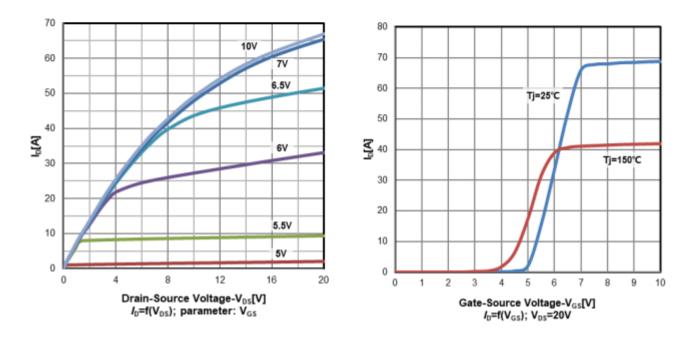


TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

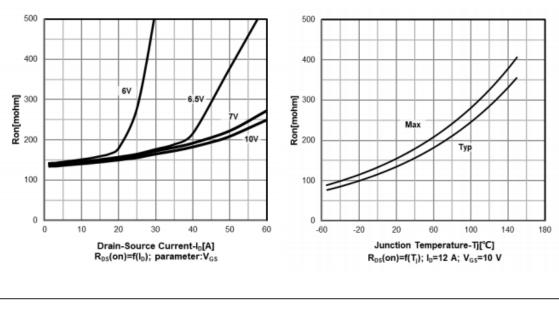


Typ. output characteristics T_i =25 $^{\circ}C$

Typ. transfer characteristics

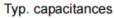




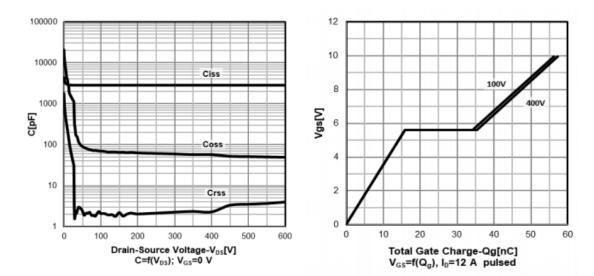


Typ. drain-source on-state resistance

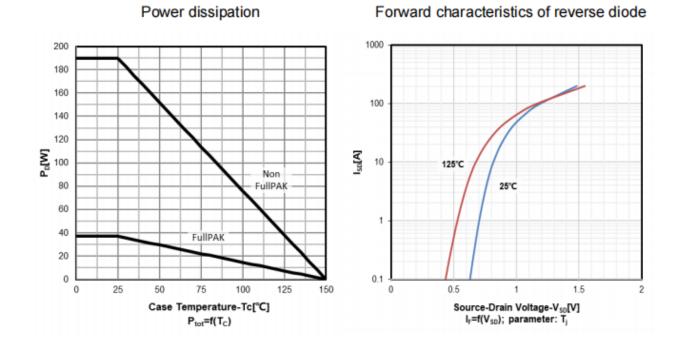
On resistance vs temperature





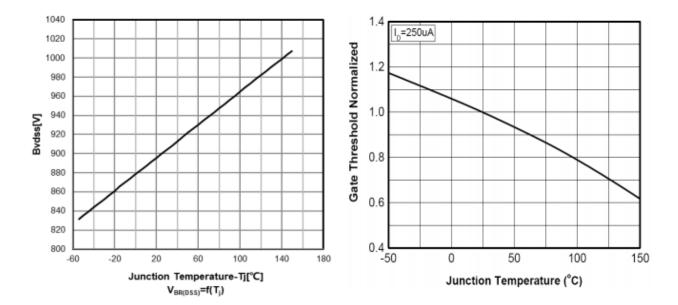






Drain-source breakdown voltage

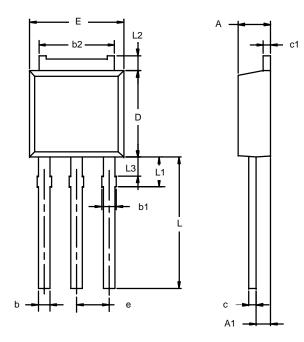
Normalized V_{GS(th)} characteristics



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Note: Dimension L3 is for reference only.

| | MILLI | METERS | INCHES | | |
|-----|----------|--------|-----------|-------|--|
| Dim | Min | Max | Min | Max | |
| Α | 2.21 | 2.38 | 0.087 | 0.094 | |
| A1 | 0.89 | 1.14 | 0.035 | 0.045 | |
| b | 0.71 | 0.89 | 0.028 | 0.035 | |
| b1 | 0.76 | 1.14 | 0.030 | 0.045 | |
| b2 | 5.23 | 5.43 | 0.206 | 0.214 | |
| С | 0.46 | 0.58 | 0.018 | 0.023 | |
| c1 | 0.46 | 0.58 | 0.018 | 0.023 | |
| D | 5.97 | 6.22 | 0.235 | 0.245 | |
| Е | 6.48 | 6.73 | 0.255 | 0.265 | |
| е | 2.28 BSC | | 0.090 BSC | | |
| L | 8.89 | 9.53 | 0.350 | 0.375 | |
| L1 | 1.91 | 2.28 | 0.075 | 0.090 | |
| L2 | 0.89 | 1.27 | 0.035 | 0.050 | |
| L3 | 1.15 | 1.52 | 0.045 | 0.060 | |

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